

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10725933			
<b>Filing Date:</b>	03-Dec-2003			
<b>Title of Invention:</b>	Fan out type wafer level package structure and method of the same			
First Named Inventor/Applicant Name:	Wen-Kun Yang			
<b>Filer:</b>	Michael Aaron Jaffe/Laura Cahill			
<b>Attorney Docket Number:</b>	HK9225US			
Filed as Large Entity				
<b>Utility Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Submission- Information Disclosure Stmt	1806	1	180	180
<b>Total in USD (\$)</b>				<b>180</b>